

### **General Description**

The MAX4030E/MAX4031E unity-gain stable op amps combine high-speed performance, rail-to-rail outputs, and ±15kV ESD protection. Targeted for applications where an input or an output is exposed to the outside world, such as video and communications, these devices are compliant with International ESD Standards: ±15kV IEC 1000-4-2 Air-Gap Discharge. ±8kV IEC 1000-4-2 Contact Discharge, and the ±15kV Human Body Model.

The MAX4030E/MAX4031E operate from a single 5V supply and consume only 12mA of quiescent supply current per amplifier while achieving a 144MHz -3dB bandwidth, 20MHz 0.1dB gain flatness, and a 115V/µs slew rate. The MAX4031E provides individual shutdown control for each of the amplifiers.

The dual MAX4030E is available in 8-pin µMAX and SO packages, and the triple MAX4031E is available in 14pin TSSOP and SO packages. All devices are specified over the -40°C to +85°C extended temperature range.

### Features

- ♦ ESD-Protected Video Inputs and Outputs ±15kV - Human Body Model ±8kV - IEC 1000-4-2 Contact Discharge ±15kV – IEC 1000-4-2 Air-Gap Discharge
- **♦ 5V Single-Supply Operation**
- ♦ 0.1µA Low-Power Shutdown Mode (MAX4031E)
- ♦ Input Common-Mode Range Extends to Ground
- ♦ 2Vp-p Large-Signal -3dB BW > 50MHz
- ♦ Directly Drives 150Ω Loads
- ♦ Low Differential Gain/Phase: 0.2%/0.2°
- **♦** -40°C to +85°C Extended Temperature Range
- ♦ Compact 8-Pin µMAX and 14-Pin TSSOP **Packages**

### **Applications**

Set-Top Boxes Standard Definition Television (SDTV) **Enhanced Television** (ETV)

**High-Definition** Television (HDTV) Notebooks **Projectors** 

Security Video Systems

Camcorders

Digital Still Cameras Portable DVD Players

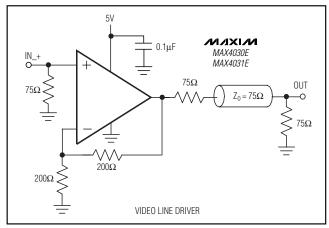
## **Ordering Information**

PART	TEMP RANGE	PIN-PACKAGE
MAX4030EEUA	-40°C to +85°C	8 µMAX
MAX4030EESA	-40°C to +85°C	8 SO
MAX4031EEUD	-40°C to +85°C	14 TSSOP
MAX4031EESD	-40°C to +85°C	14 SO

## **Pin Configurations**

#### TOP VIEW SHDNA 14 OUTC OUTA 1 8 V<sub>CC</sub> SHDNC 2 13 INC-INA- 2 MIXIM OUTB SHDNB 3 12 INC+ MAX4030E MIXIM INA+ 3 INB-MAX4031E 11 GND V<sub>CC</sub> 4 GND 4 5 INB+ INA+ 5 10 INB+ INA-9 INBμ**MAX/SO** OUTA 8 OUTB TSSOP/SO

## Typical Operating Circuit



MIXIM

### **ABSOLUTE MAXIMUM RATINGS**

(All voltages referenced to GND, unless otherwise no	ted.)
V <sub>CC</sub> 0	.3V to +6V
IN, IN_+, OUT_, SHDN0.3V to (V	CC + 0.3V)
Current into IN, IN_+, SHDN	±20mA
Output Short-Circuit Duration to VCC or GND	Continuous
Continuous Power Dissipation ( $T_A = +70^{\circ}C$ )	
8-Pin µMAX (derate 4.5mW/°C above +70°C)	
8-Pin SO (derate 5.9mW/°C above +70°C)	471mW

14-Pin TSSOP (derate 9.1mW/°C above +70°C)72	7mW
14-Pin SO (derate 8.3mW/°C above +70°C)66	7mW
Operating Temperature Range40°C to +	85°C
Junction Temperature+1	50°C
Storage Temperature Range65°C to +1	
Lead Temperature (soldering, 10s)+3	00°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

### DC ELECTRICAL CHARACTERISTICS

 $(V_{CC} = 5V, V_{CM} = 0V, V_{OUT} = V_{CC}/2, \overline{SHDN} = V_{CC}, R_L = \infty \text{ to } V_{CC}/2, T_A = T_{MIN} \text{ to } T_{MAX}, \text{ unless otherwise noted. Typical values are at } T_A = +25^{\circ}C.) \text{ (Note 1)}$ 

PARAMETER	SYMBOL	CON	IDITIONS	MIN	TYP	MAX	UNITS	
Operating Supply Voltage Range	Vcc	Guaranteed by PSRR		4.5		5.5	V	
Quiescent Current (per Amplifier)	Icc				12	22	mA	
Shutdown Current (per Amplifier)	ISHDN	SHDN_ = GND (MAX	4031E)		0.1	10	μΑ	
Input Common-Mode Voltage	V <sub>CM</sub>	Guaranteed by CMRF	3	0		V <sub>CC</sub> - 2.25	V	
Input Offset Voltage	Vos	T <sub>A</sub> = +25°C			5	13	mV	
		$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$				26		
Input Offset Voltage Matching	ΔVos				2.6		mV	
Input Offset Voltage Tempco	TC <sub>VOS</sub>				31		μV/°C	
Input Bias Current	ΙB				0.01	1	μΑ	
Input Offset Current	los				0.01		μΑ	
Input Resistance	RIN				1		GΩ	
Common-Mode Rejection Ratio	CMRR	GND ≤ V <sub>CM</sub> ≤ V <sub>CC</sub> - 2	2.25V	50	70		dB	
Power-Supply Rejection Ratio	PSRR	$4.5V \le V_{CC} \le 5.5V$		40	60		dB	
	Avol	$0.5V \le V_{OUT} \le 4.5V$ ,	$R_L = 2k\Omega$ to $V_{CC}/2$		80			
Open-Loop Gain		$0.6V \le V_{OUT} \le 4.4V$ , $R_L = 150\Omega$ to $V_{CC}/2$		50	70		dB	
		$0.4V \le V_{OUT} \le 3.5V$ ,	$R_L = 150\Omega$ to GND	50	70			
		D. 01:0 to V = -/0	V <sub>CC</sub> - V <sub>OH</sub>		0.05			
	V <sub>OUT</sub> _	H	$R_L = 2k\Omega$ to $V_{CC}/2$	V <sub>OL</sub> - GND		0.05		
Output Valtage Cuing		$R_L = 150\Omega$ to $V_{CC}/2$	V <sub>CC</sub> - V <sub>OH</sub>		0.15	0.4	- - -	
Output Voltage Swing			V <sub>OL</sub> - GND		0.15	0.4		
		$R_L = 150\Omega$ to GND	V <sub>CC</sub> - V <sub>OH</sub>		0.3	0.8		
			V <sub>OL</sub> - GND		0.01	0.05		
Output Short-Circuit Current	Isc	Sinking or sourcing			±100		mA	
SHDN_ Logic Threshold	VIL	MAX4031E MAX4031E				0.8	V	
	VIH			2.0				
OUDN Lastic last Course	Ι <sub>Ι</sub> L	SHDN_ = GND (MAX-	4031E)		0.10	10		
SHDN_ Logic Input Current	lіН	SHDN_ = V <sub>CC</sub> (MAX	4031E)		0.10	10	μΑ	

### DC ELECTRICAL CHARACTERISTICS (continued)

 $(V_{CC} = 5V, V_{CM} = 0V, V_{OUT} = V_{CC}/2, \overline{SHDN} = V_{CC}, R_L = \infty \text{ to } V_{CC}/2, T_A = T_{MIN} \text{ to } T_{MAX}, \text{ unless otherwise noted. Typical values are at } T_A = +25^{\circ}C.) \text{ (Note 1)}$ 

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Disabled Output Leakage Current	lout_sh	SHDN_ = GND (MAX4031E)		0.1	10	μΑ
		Human Body Model		±15		
ESD Protection Voltage (Note 2)		IEC 1000-4-2 Contact Discharge		±8		kV
		IEC 1000-4-2 Air-Gap Discharge		±15		

### **AC ELECTRICAL CHARACTERISTICS**

 $(V_{CC} = 5V, V_{CM} = 1.5V, R_L = 150\Omega \text{ to GND}, \overline{SHDN}_{-} = V_{CC}, A_{VCL}_{-} = +2V/V, T_A = +25^{\circ}C, \text{ unless otherwise noted.})$ 

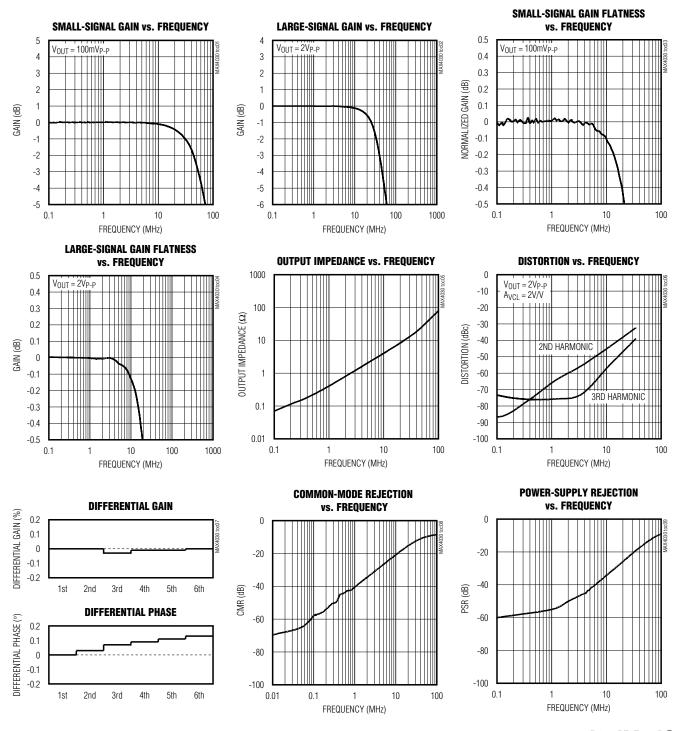
PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	
Small Signal 2dP Pandwidth	DWoo	$V_{OUT} = 100 \text{mV}_{P-P}, A_{VCL} = +1 \text{V/V}$		144		MHz	
Small-Signal -3dB Bandwidth	BW <sub>SS</sub>	$V_{OUT} = 100 \text{mV}_{P-P}, A_{VCL} = +2 \text{V/V}$		53			
Large-Signal -3dB Bandwidth	BW. o	$V_{OUT} = 2V_{P-P}$ , $A_{VCL} = +1V/V$		52		MHz	
Large-Signal -30B Barldwidth	BW <sub>LS</sub>	$V_{OUT} = 2V_{P-P}$ , $A_{VCL} = +2V/V$		40			
Small-Signal 0.1dB Gain Flatness	RWo 4 JD00	$V_{OUT} = 100 \text{mV}_{P-P}, A_{VCL} = +1 \text{V/V}$		20		MHz	
Sitiali-Signal U. Tub Gain Flattiess	BW <sub>0.1dBSS</sub>	$V_{OUT} = 100 \text{mV}_{P-P}, A_{VCL} = +2 \text{V/V}$		10			
Large-Signal 0.1dB Gain Flatness	BW <sub>0.1dBLS</sub>	$V_{OUT} = 2V_{P-P}$ , $A_{VCL} = +1V/V$		20		MHz	
Large-Signal 0. 10B Gaill Flathess	DVV0.1dBLS	$V_{OUT} = 2V_{P-P}$ , $A_{VCL} = +2V/V$		9		IVII IZ	
Slew Rate	SR	V <sub>OUT</sub> _ = 2V step		15		V/µs	
Settling Time to 0.1%	ts	V <sub>OUT</sub> _ = 2V step		40		ns	
Channel-to-Channel Isolation	CH <sub>ISO</sub>	f = 4.43MHz		65		dB	
Differential Phase Error	DP	NTSC, $R_L = 150\Omega$ to GND, $A_{VCL} = +2V/V$		0.2		Degrees	
Differential Gain Error	DG	NTSC, $R_L = 150\Omega$ to GND, $A_{VCL} = +2V/V$		0.2		%	
Input Capacitance	CIN			8		рF	
Capacitive-Load Stability		No sustained oscillations		200		рF	
Output Impedance	Zout	f = 4.43MHz		2		Ω	
Enable Time	ton	V <sub>IN</sub> _ = 1V (MAX4031E)		2		μs	
Disable Time	toff	V <sub>IN</sub> _ = 1V (MAX4031E)		0.15		μs	

**Note 1:** All devices are 100% production tested at  $T_A = +25$ °C. Specifications over temperature limits are guaranteed by design.

Note 2: ESD protection is specified for test point A and test point B only (Figure 7).

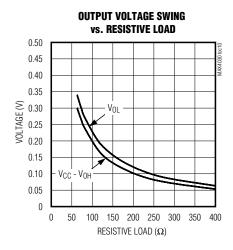
## Typical Operating Characteristics

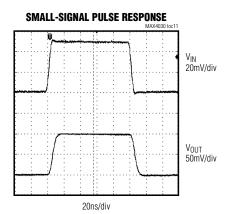
 $(V_{CC} = 5V, V_{CM} = 1.5V, A_{VCL} = +2V/V, R_L = 150\Omega$  to  $V_{CC}/2, T_A = +25$ °C, unless otherwise noted.)

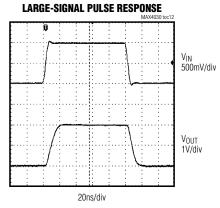


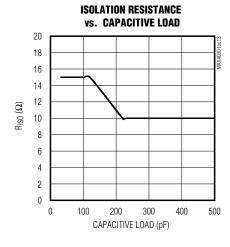
## Typical Operating Characteristics (continued)

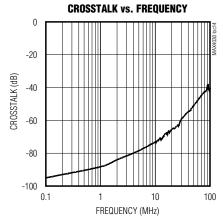
 $(V_{CC} = 5V, V_{CM} = 1.5V, A_{VCL} = +2V/V, R_L = 150\Omega \text{ to } V_{CC}/2, T_A = +25^{\circ}C, \text{ unless otherwise noted.})$ 











### **Pin Description**

PIN		N. A. B. A. E.	FUNCTION	
MAX4030E	MAX4031E	NAME	FUNCTION	
1	7	OUTA	Amplifier A Output	
2	6	INA-	Amplifier A Inverting Input	
3	5	INA+	Amplifier A Noninverting Input	
4	11	GND	Ground	
5	10	INB+	Amplifier B Noninverting Input	
6	9	INB-	Amplifier B Inverting Input	
7	8	OUTB	Amplifier B Output	
8	4	Vcc	Positive Power Supply. Bypass V <sub>CC</sub> to GND with a 0.1µF capacitor.	
_	1	SHDNA	Amplifier A Shutdown Input. Connect SHDNA high to enable amplifier A.	
_	2	SHDNC	Amplifier C Shutdown Input. Connect SHDNC high to enable amplifier C.	
_	3	SHDNB	Amplifier B Shutdown Input. Connect SHDNB high to enable amplifier B.	
_	12	INC+	Amplifier C Noninverting Input	
_	13	INC-	Amplifier C Inverting Input	
_	14	OUTC	Amplifier C Output	

### **Detailed Description**

The MAX4030E/MAX4031E dual/triple, 5V operational amplifiers achieve 115V/µs slew rates and 144MHz bandwidths. High ±15kV ESD protection at video inputs and outputs guards against unexpected discharge. Excellent harmonic distortion and differential gain/phase performance make these amplifiers an ideal choice for a wide variety of video and RF signal-processing applications.

#### **Ground-Sensing Inputs**

The MAX4030E/MAX4031E input stage can sense common-mode voltages from ground to within 2.25V of the positive supply.

#### Rail-to-Rail Outputs

The MAX4030E/MAX4031E rail-to-rail outputs can swing to within 100mV of each supply because local feedback around the output stage ensures low open-loop output impedance, reducing gain sensitivity to load variations.

#### Shutdown (MAX4031E Only)

The MAX4031E offers individual shutdown control for each amplifier. Drive SHDN\_ low to shut down the amplifier. In shutdown, the amplifier output impedance is high impedance.

## \_Applications Information

#### **Choosing Resistor Values**

#### **Unity-Gain Configuration**

The MAX4030E/MAX4031E are internally compensated for unity gain. When configured for unity gain, a  $24\Omega$  resistor (RF) in series with the feedback path optimizes AC performance. This resistor improves AC response by reducing the Q of the parallel LC circuit formed by the parasitic feedback capacitance and lead inductance.

#### Video Line Driver

The MAX4030E/MAX4031E are low-power, voltage-feedback amplifiers featuring bandwidths up to 40MHz and 0.1dB gain flatness to 9MHz. They are designed to minimize differential-gain error and differential-phase error to 0.2% and 0.2°, respectively. They have a 40ns settling time to 0.1%, 110V/µs slew rates, and output-current-drive capability of up to 50mA, making them ideal for driving video loads.

#### Inverting and Noninverting Configurations

Select the feedback (RF) and input (RG) resistor values to fit the gain requirements of the application. Large resistor values increase voltage noise and interact with the amplifier's input and PC board capacitance. This can generate undesirable poles and zeros and

NIXLN ......

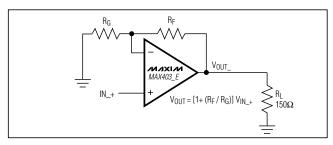


Figure 1. Noninverting Gain Configuration

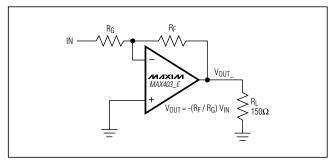


Figure 2. Inverting Gain Configuration

decrease bandwidth or cause oscillations. For example, a noninverting gain-of-two configuration (RF = RG) using  $2k\Omega$  resistors, combined with 4pF of amplifier input capacitance and 1pF of PC board capacitance, cause a pole at 79.6MHz. Since this pole is within the amplifier bandwidth, it jeopardizes stability. Reducing the  $2k\Omega$  resistors to  $100\Omega$  extends the pole frequency to 1.59GHz, but could limit output swing by adding  $200\Omega$  in parallel with the amplifier's load resistor (Figures 1 and 2).

#### Layout and Power-Supply Bypassing

These amplifiers operate from a single 5V power supply. Bypass VCC to ground with a  $0.1\mu F$  capacitor as close to VCC as possible. Maxim recommends using microstrip and stripline techniques to obtain full bandwidth. To ensure that the PC board does not degrade the amplifier's performance, design it for a frequency greater than 1GHz. Pay careful attention to inputs and outputs to avoid large parasitic capacitance. Under all conditions observe the following design guidelines:

- Do not use wire-wrap boards. Wire-wrap boards are too inductive.
- Do not use IC sockets. Sockets increase parasitic capacitance and inductance.
- Use surface mount instead of through-hole components for better high-frequency performance.

- Use a PC board with at least two layers. The PC board should be as free from voids as possible.
- Keep signal lines as short and as straight as possible. Do not make 90° turns; round all corners.

#### **Output Capacitive Loading and Stability**

The MAX4030E/MAX4031E are optimized for AC performance and do not drive highly reactive loads, which decreases phase margin and can produce excessive ringing and oscillation. Figure 3 shows a circuit modification that uses an isolation resistor (RISO) to eliminate this problem. Figure 4 shows a graph of the Optimal Isolation Resistor (RISO) vs. Capacitive Load. Figure 5 shows how a capacitive load causes excessive peaking of the amplifier's frequency response if the capacitor is not isolated from the amplifier by a resistor. A small isolation resistor (usually  $10\Omega$  to  $15\Omega$ ) placed before the reactive load prevents ringing and oscillation. At higher capacitive loads, the interaction of the load capacitance and the isolation resistor controls the AC performance. Figure 6 shows the effect of a  $10\Omega$ isolation resistor on closed-loop response.

#### **ESD Protection**

As with all Maxim devices, ESD protection structures are incorporated on all pins to protect against ESD encountered during handling and assembly. Input and output pins of the MAX4030E/MAX4031E have extra protection against static electricity. Maxim's engineers have developed state-of-the-art structures enabling these pins to withstand ESD up to ±15kV without damage when placed in the test circuit (Figure 7). The MAX4030E/MAX4031E are characterized for protection to the following limits:

- ±15kV using the Human Body Model
- ±8kV using the Contact Discharge method specified in IEC 1000-4-2
- ±15kV using the Air-Gap Discharge method specified in IEC 1000-4-2

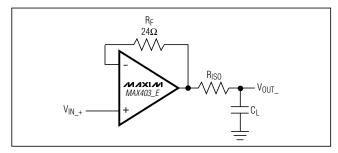


Figure 3. Driving a Capacitive Load Through an Isolation Resistor

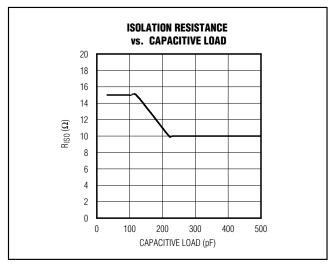


Figure 4. Isolation Resistance vs. Capacitive Load

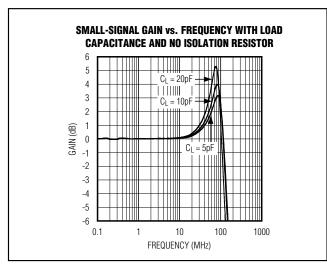


Figure 5. Small-Signal Gain vs. Frequency with Load Capacitance and No Isolation Resistor

#### Human Body Model

Figure 8 shows the Human Body Model and Figure 9 shows the current waveform it generates when discharged into low impedance. This model consists of a 150pF capacitor charged to the ESD voltage of interest, and then discharged into the test device through a  $1.5k\Omega$  resistor.

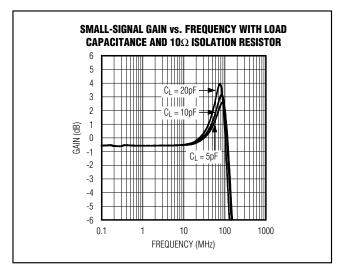


Figure 6. Small-Signal Gain vs. Frequency with Load Capacitance and  $10\Omega$  Isolation Resistor

#### IEC 1000-4-2

The IEC 1000-4-2 standard covers ESD testing and performance of finished equipment; it does not specifically refer to ICs. The MAX4030E/MAX4031E enable the design of equipment that meets the highest level (level 4) of IEC 1000-4-2 without the need for additional ESD protection components. The major difference between tests done using the Human Body Model and IEC 1000-4-2 is higher peak current in IEC 1000-4-2. Because series resistance is lower in the IEC 1000-4-2 model, the ESD-withstand voltage measured to this standard is generally lower than that measured using the Human Body. Figure 10 shows the IEC 1000-4-2 model and Figure 11 shows the current waveform for the ±8kV IEC 1000-4-2 level 4 ESD Contact Discharge test. The Air-Gap test involves approaching the device with a charged probe. The Contact Discharge method connects the probe to the device before the probe is energized.

## Chip Information

MAX4030E TRANSISTOR COUNT: 271 MAX4031E TRANSISTOR COUNT: 387

PROCESS: BICMOS

8 \_\_\_\_\_\_ /N/XI/N

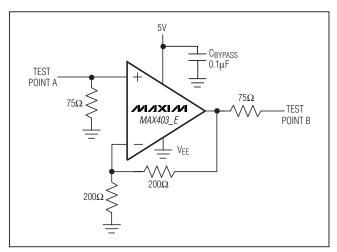


Figure 7. ESD Test Circuit

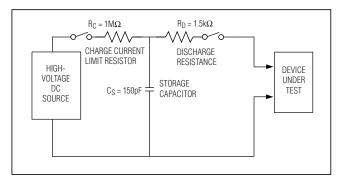


Figure 8. Human Body ESD Model

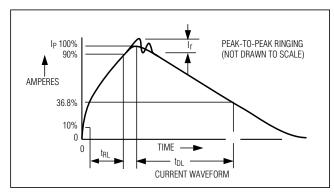


Figure 9. Human Body Current Waveform

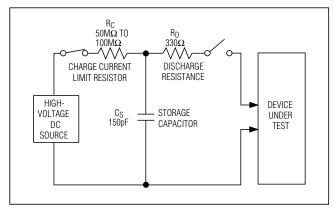


Figure 10. IEC 1000-4-2 ESD Test Model

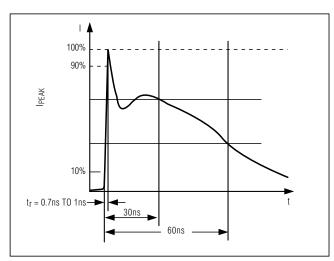
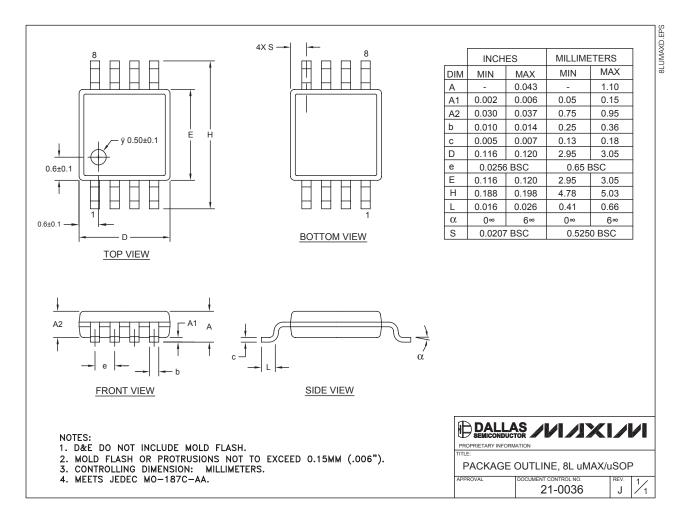


Figure 11. IEC 1000-4-2 ESD Generator Current Waveform

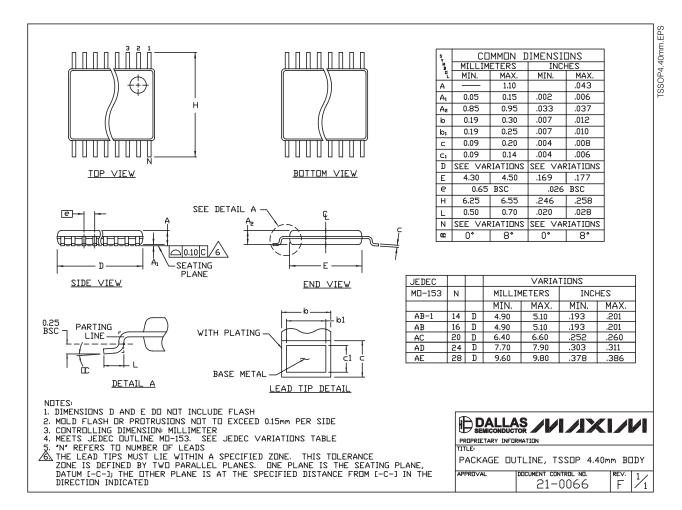
## Package Information

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to <a href="https://www.maxim-ic.com/packages">www.maxim-ic.com/packages</a>.)



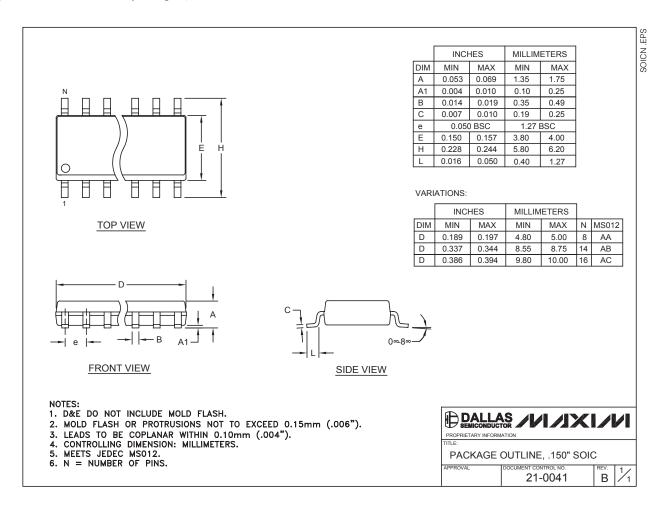
## Package Information (continued)

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to <a href="https://www.maxim-ic.com/packages">www.maxim-ic.com/packages</a>.)



### Package Information (continued)

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to <a href="https://www.maxim-ic.com/packages">www.maxim-ic.com/packages</a>.)



Maxim cannot assume responsibility for use of any circuitry other than circuitry entirely embodied in a Maxim product. No circuit patent licenses are implied. Maxim reserves the right to change the circuitry and specifications without notice at any time.